

Nayu Li

List of Publications by Year in descending order

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Version: 2024-02-01

10
papers

86
citations

1478505

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57
citing authors

| # | ARTICLE | IF | CITATIONS |
|----|--|-----|-----------|
| 1 | A Four-Element 7.5–9-GHz Phased-Array Receiver With 8 Simultaneously Reconfigurable Beams in 65-nm CMOS. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2021, 69, 1114-1126. | 4.6 | 17 |
| 2 | A 6.5–12-GHz Balanced Variable-Gain Low-Noise Amplifier With Frequency-Selective Gain Equalization Technique. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2021, 69, 732-744. | 4.6 | 14 |
| 3 | A 4-Element 7.5-9 GHz Phased Array Receiver with 8 Simultaneously Reconfigurable Beams in 65 nm CMOS Technology. , 2020, , . | | 10 |
| 4 | An 800-ps Origami True-Time-Delay-Based CMOS Receiver Front End for 6.5–9-GHz Phased Arrays. <i>IEEE Solid-State Circuits Letters</i> , 2020, 3, 382-385. | 2.0 | 8 |
| 5 | A DC–Ka-Band 7-Bit Passive Attenuator With Capacitive-Compensation-Based Bandwidth Extension Technique in 55-nm CMOS. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2021, 69, 3861-3874. | 4.6 | 8 |
| 6 | A DC–28-GHz 7-Bit High-Accuracy Digital-Step Attenuator in 55-nm CMOS. <i>IEEE Microwave and Wireless Components Letters</i> , 2022, 32, 157-160. | 3.2 | 8 |
| 7 | A DC-32GHz 7-Bit Passive Attenuator with Capacitive Compensation Bandwidth Extension Technique in 55 nm CMOS. , 2020, , . | | 7 |
| 8 | A 6.5-12 GHz Balanced Variable Gain Low-Noise Amplifier with Frequency-Selective Non-Foster Gain Equalization Technique. , 2020, , . | | 7 |
| 9 | A Calibration Scheme for 24–28-GHz Variable-Gain Phase Shifter in 65-nm CMOS. <i>IEEE Transactions on Circuits and Systems II: Express Briefs</i> , 2022, 69, 1996-2000. | 3.0 | 6 |
| 10 | Design and Analysis of a 26–34.5-GHz Power Amplifier With Balanced Mismatch Reduction and Interstage Matching. <i>IEEE Microwave and Wireless Components Letters</i> , 2022, 32, 968-971. | 3.2 | 1 |